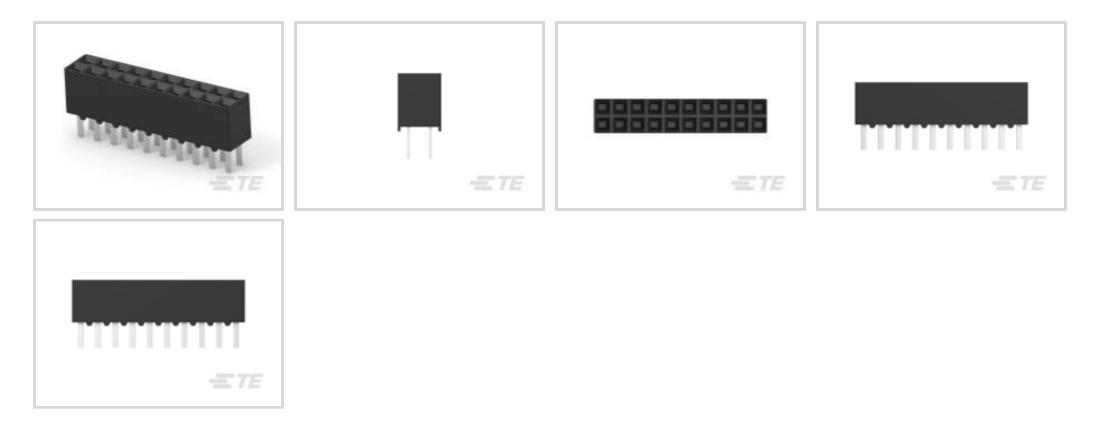


AMPMODU | Modu Connector System

TE Internal #: 1-534998-0 PCB Mount Receptacle, Vertical, Board-to-Board, 20 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 20

Number of Rows: 2

Features

E

Product Type Features

Applied Pressure	Standard	
PCB Connector Assembly Type	PCB Mount Receptacle	
Connector System	Board-to-Board	
Sealable	No	
Connector & Contact Terminates To	Printed Circuit Board	
Configuration Features		
Stackable	Yes	
PCB Mount Orientation	Vertical	
Number of Positions	20	
Number of Rows	2	
Board-to-Board Configuration	Parallel	
Electrical Characteristics		
Dielectric Withstanding Voltage (Max)	750 VAC	
Insulation Resistance	5000 ΜΩ	

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Operating Voltage	333 VAC	
Body Features		
Connector Profile	Low	
Primary Product Color	Black	
Contact Features		
Contact Protection Type	Closed Entry Housing	
Contact Mating Area Length	3.77 mm[.148 in]	
Mating Square Post Dimension	.64 mm[.025 in]	
PCB Contact Termination Area Plating Material Thickness	3.81 – 7.61 µm	
Contact Shape & Form	Round	
PCB Contact Termination Area Plating Material	Tin-Lead	
Contact Base Material	Phosphor Bronze	
Contact Mating Area Plating Material	Gold	
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]	
Contact Type	Socket	
Contact Current Rating (Max)	2 A	

Termination Features

Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]	
Rectangular Termination Post & Tail Width	.7 mm[.028 in]	
Termination Post & Tail Length	3.18 mm[.125 in]	
Termination Method to Printed Circuit Board	Through Hole - Solder	
Mechanical Attachment		
Mating Alignment	Without	
PCB Mount Retention	Without	
PCB Mount Alignment	Without	
Connector Mounting Type	Board Mount	
Housing Features		
Mating Entry Location	Тор	
Centerline (Pitch)	2.54 mm[.1 in]	
Housing Material	Thermoplastic	
Dimensions		
Connector Height	5.03 mm[.198 in]	

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Row-to-Row Spacing	2.54 mm[.1 in]	
Stack Height	9.02 mm[.355 in]	
PCB Thickness (Recommended)	1.57 mm[.055 – .094 in]	
Usage Conditions		
Housing Temperature Rating	Standard	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]	
Operation/Application		
Solder Process Feature	Board Standoff	
Circuit Application	Signal	
Industry Standards		
Approved Standards	CSA LR7189, UL E28476	
UL Flammability Rating	UL 94V-0	
Packaging Features		
Packaging Quantity	22	
Packaging Type	Box, Tube	

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant	
EU ELV Directive 2000/53/EC	Compliant with Exemptions	
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold	
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) SVHC > Threshold: Pb (13% in Component) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.	
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.	
Solder Process Capability	Wave solder capable to 240°C	

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent

PCB Mount Receptacle, Vertical, Board-to-Board, 20 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



Also in the Series | Modu Connector System



Automotive Housings(2)	Board-to-Board Jumpers & Shunts(5)	PCB Connector Covers(4)	PCB Connector Keying(4)

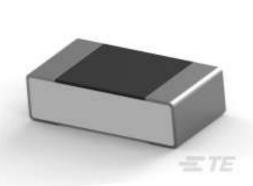


Customers Also Bought

PCB Mount Receptacle, Vertical, Board-to-Board, 20 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System







TE Part #3-2176370-9 RQ 0603 1K07 0.1% 10PPM 5K RL

Documents

Product Drawings 20 MODIV VRT DR CE 100/125

English

CAD Files

Customer View Model ENG_CVM_CVM_1-534998-0_R.2d_dxf.zip

English

3D PDF

3D

Customer View Model ENG_CVM_CVM_1-534998-0_R.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-534998-0_R.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

C For support call+1 800 522 6752

PCB Mount Receptacle, Vertical, Board-to-Board, 20 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



Application Specification

English